LNA4801L

GaAlAs Infrared Light Emitting Diode

For optical control systems

■ Features

• Fast response and high-speed modulation capability:

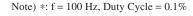
 $f_C = 20 \text{ MHz (typ.)}$

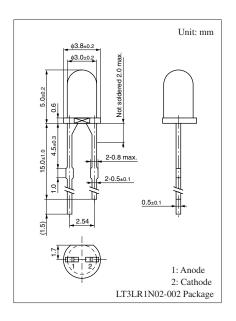
• Wide directivity: $\theta = 22^{\circ}$ (typ.)

• Transparent epoxy resin package

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	3	V
Forward current	I_{F}	100	mA
Pulse forward current *	I_{FP}	1	A
Power dissipation	P_{D}	190	mW
Operating ambient temperature	T_{opr}	-25 to +85	°C
Storage temperature	T_{stg}	-30 to +100	°C





\blacksquare Electrical-Optical Characteristics $\rm T_a = 25^{\circ}C \pm 3^{\circ}C$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	V_{F}	$I_F = 100 \text{ mA}$		1.6	1.9	V
Reverse current	I_R	$V_R = 3 V$			10	μΑ
Center radiant intensity	I _e	$I_F = 50 \text{ mA}$	12		48	mW/sr
Peak emission wavelength *	λ_{P}	$I_F = 50 \text{ mA}$		860		nm
Spectral half band width *	Δλ	$I_F = 50 \text{ mA}$		40		nm
Half-power angle	θ	The angle when the radiant power is halved		22		0

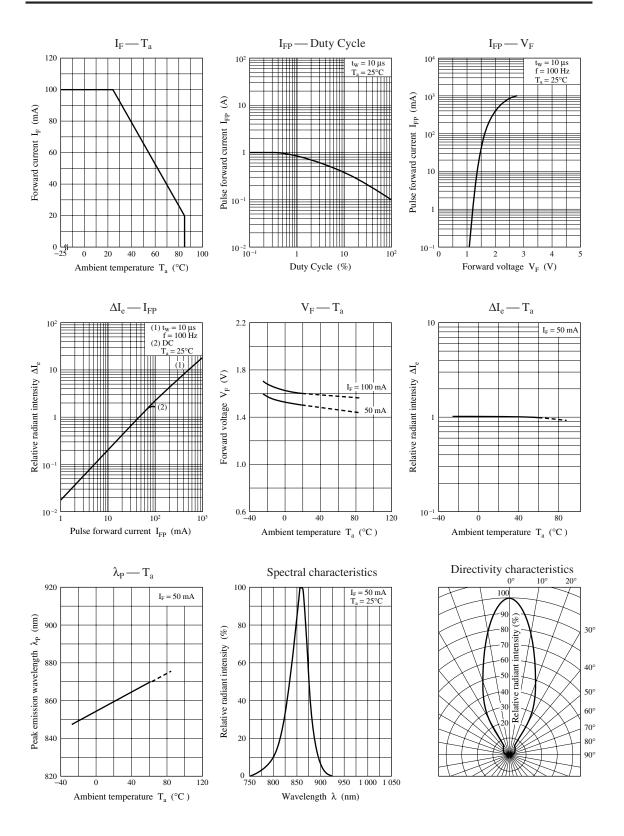
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. Modulation total power output 3 dB frequency to fall from 1 MHz.

Cutoff frequency: 20 MHz

$$f_C$$
: 10 × log $\frac{P_O \text{ at } f = f_C}{P_O \text{ at } f = 1 \text{ MHz}} = -3$

3. *: LED might radiate red light under large current drive.



Caution for Safety

⚠ DANGER

■ This product contains Gallium Arsenide (GaAs).

GaAs powder and vapor are hazardous to human health if inhaled or ingested. Do not burn, destroy, cut, cleave off, or chemically dissolve the product. Follow related laws and ordinances for disposal. The product should be excluded form general industrial waste or household garbage.

Request for your special attention and precautions in using the technical information and semiconductors described in this material

- (1) An export permit needs to be obtained from the competent authorities of the Japanese Government if any of the products or technical information described in this material and controlled under the "Foreign Exchange and Foreign Trade Law" is to be exported or taken out of Japan.
- (2) The technical information described in this material is limited to showing representative characteristics and applied circuits examples of the products. It neither warrants non-infringement of intellectual property right or any other rights owned by our company or a third party, nor grants any license.
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- (4) The products described in this material are intended to be used for standard applications or general electronic equipment (such as office equipment, communications equipment, measuring instruments and household appliances).

Consult our sales staff in advance for information on the following applications:

- Special applications (such as for airplanes, aerospace, automobiles, traffic control equipment, combustion equipment, life support systems and safety devices) in which exceptional quality and reliability are required, or if the failure or malfunction of the products may directly jeopardize life or harm the human body.
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 - Even when the products are used within the guaranteed values, take into the consideration of incidence of break down and failure mode, possible to occur to semiconductor products. Measures on the systems such as redundant design, arresting the spread of fire or preventing glitch are recommended in order to prevent physical injury, fire, social damages, for example, by using the products.
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